

Electronic Acknowledgement Receipt

EFS ID:	1196400
Application Number:	10618113
Confirmation Number:	8697
Title of Invention:	Wafer-level chip scale package and method for fabricating and using the same
First Named Inventor:	Rajeev Joshi
Customer Number:	27966
Filer:	kenneth E. Horton/Erin Cowles
Filer Authorized By:	kenneth E. Horton
Attorney Docket Number:	11948.21
Receipt Date:	12-SEP-2006
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Application Type:	Utility
International Application Number:	

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Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment - After Non-Final Rejection	4OAreponsefiled.pdf	769736	no	8

Warnings:**Information:****Total Files Size (in bytes):**

769736

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.